



PATENT ABSTRACTS OF JAPAN

(11) Publication number: 06291481 A

(43) Date of publication of application: 18.10.1994

(51) Int. Cl. H05K 7/20

H01L 23/427, H05K 1/02, H05K 1/14

(21) Application number: 05100211

(22) Date of filing: 02.04.1993

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YAMAMORI KAZUYUKI
HAMADA HIROKI
KOBAYASHI KENZO(54) HIGH-DENSITY HEAT RADIATION TYPE
CIRCUIT BOARD

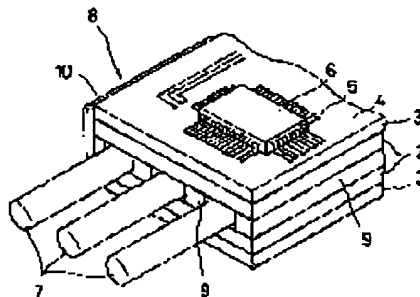
(57) Abstract:

PURPOSE: To increase the mounting area of a heat radiation type circuit board where heating components such as a semiconductor element, etc., are mounted, and cope easily with specification change, and besides, facilitate the maintenance.

CONSTITUTION: This is a high-density heat radiation type circuit board where a plurality of sheets of heat radiation type circuit boards being made by uniting printed circuit boards 3 with heat sinks 2 are combined up and down so that the printed circuit board faces may surface and heat pipes 7 are arranged

through a spacer 9 at the heat sinks on the inside, and also the printed circuit boards are coupled with each other by a coupling 10.

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